

Listing of Claims

Claim 1 (currently amended): An electrolyte tin-plating solution, having a pH value of 1.5-6.0 and comprising:

- (1) 5-60 g/L of tin(II) ion,
- (2) a complexing agent,
- (3) one or more non-ionic surfactants chosen from polyoxyethylene lauryl ether, polyoxyethylene polyoxypropylene glycol with an average of 10 units of ethylene oxide and an average of 4 units of propylene oxide and polyoxyethylene nonyl phenyl ether with an average of 9 units of ethylene oxide, ~~and~~
- (4) 0.01-0.5 g/L of bismuth(III) ion, and
- (5) a conducting salt, an anode-dissolving agent or an antioxidant.

Claims 2-3 (canceled)

Claim 4 (previously presented): A method for electrolytic tin plating, characterized by using the electrolytic tin plating solution of claim 1 for electrolytic tin plating on electronic parts.

Claim 5 (previously presented): The electrolytic tin-plating solution of claim 1, wherein the non-ionic surfactants range from 0.1-20 g/L.

Claim 6 (previously presented): The electrolytic tin-plating solution of claim 5, wherein the non-ionic surfactants range from 0.5-5.0 g/L.

Claim 7 (new): The electrolyte tin-plating solution of claim 1, wherein the bismuth (III) ion ranges from 0.02-0.2 g/L.